JEITA EDA -WG Activity

Study of Interconnect Model

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Contents

0. Measurement and Simulation Environment

0.1 Measurement equipment and simulation tools

1. Detail of Measurement and simulation

- 1.1 Measurement
- 1.2 Simulation
- 2. Comparison between Measurement and Simulation 2.1 Eye-Diagram and Discrete Waveform
 - Simulation with Moscured EDA mod
- 3. Simulation with Measured EDA models
 - 3.1 Eye-Diagram
- 4. Accuracy of EDA models
 - 4.1 TDR waveform for PCB trace
 - 4.2 S-parameters of device models (Filters, Via, Connector, Cable)
- 5. Conclusion

0.1. Measurement equipment and simulation tools

- 0.1.1 Equipment of Measurement Time Domain Reflectmetory (TDR) 86100C +54754A(TDR module)
 - Vector Network Analyzer (VNA) N5230A PNA-L





Signal Generator (SG) with Real Time Oscilloscope (OSC) 81134A ,DSO81204B

0.1.2 Simulation tools and Venders 4 Company's Tool





1.1. Detail of Measurement

1.1.1 Measurement of Eye-diagram

Signal generator (SG) and real time oscilloscope (OSC) were used to compare measurement with simulation of Eye-Diagram. SG was used to inject differential signal which were pseudo random bit sequence. (PRBS) PRBS pattern were 255bits.

OSC was used to record transient waveform.

DUT of three types were provided, which simulate PCBs of digital consumer electronics. One of them contains only filter and connector, the others contain filter, connector and also through hole via and slit.



1.1. Detail of Measurement

1.1.2 Measurement of TDR

To verify characteristic Impedance of PCB, TDR was used. The TDR injected differential step pulse and measured reflection waveform, then characteristic Impedance was calculated by the reflection waveform.

One side of DUT were left open in order to measure DUT of electric length which is propagation time to the end ports.



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1.1. Detail of Measurement

1.1.3 Measurement of S-parameters

To verify simulation models ,VNA were used to measure S-parameters. The VNA has 4 ports, therefore it measures mixed mode S-parameters which are important parameter to investigate differential transmission line.



- EDA models were provided by component manufacturer.
 E.g. Murata, TDK, JAE
- PCB models were extracted from CAD data by simulation tools PCB manufacturer does not provide EDA model.
 They provide only layer structure, wire width, space between wires and dielectric constant.
- EDA models were S-parameters or Equivalent Circuits.

1.2. Detail of simulation Simulation Items

Eye-Diagram
 Only EDA model provided by the manufacturer.
 To verify Whether the measurement agrees with the simulation
 Measured S-parameters

To verify whether each simulator accept S-parameters.

TDR Waveform
 Only wire of PCB

To verify whether EDA model of PCB which is extracted by each simulator is correct.

S-parameters
 Each EDA models

To verify accuracy of each EDA models

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2.1 Comparison between Measurement and Simulation Eye diagram of Input conditions



To make source signal of simulation, OSC was directly connected with SG using short cable. Cable length was about 20cm.



2.2 Comparison between Measurement and Simulation #53 Eye Diagram of Measurement and Simulation



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2.3 Comparison between Measurement and Simulation #53 Eye Diagram of Measurement and Simulation



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2.5 Comparison between Measurement and Simulation #67 Eye Diagram of Measurement and Simulation



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2.7 Comparison between Measurement and Simulation #68 Eye Diagram of Measurement and Simulation



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3.2 Simulations for Measured EDA models #67 Eye Diagram of Measurement and Simulation using measured S-parameters



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3.3 Simulations for Measured EDA models #68 Eye Diagram of Measurement and Simulation using measured S-parameters



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3.4 Comparison between Measurement and Simulation SG+Cable(1m+0.3m)+Sampling OSC



SG Up to 13.5Gbps Rise time 18ps



Sampling OSC Band width 50GHz

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3.5 Comparison between Measurement and Simulation Filter+Cable,Connector+traces without Via and slit





3.6 Comparison between Measurement and Simulation Filter+Cable,Connector+slit





3.7 Comparison between Measurement and Simulation Filter+Cable,Connector+Via





3.8 Comparison between Measurement and Simulation Filter+Cable,Connector+traces without Via and slit





3.9 Comparison between Measurement and Simulation Filter+Cable,Connector+slit





3.10 Comparison between Measurement and Simulation Filter+Cable,Connector+Via





3.11 Comparison between Measurement and Simulation Filter+Cable,Connector+traces without Via and slit





3.12 Comparison between Measurement and Simulation Filter+Cable,Connector+slit





3.13 Comparison between Measurement and Simulation Filter+Cable,Connector+Via





4. Accuracy of EDA models Measured and Simulated TDR waveform 4.1 130 125 120 Meas 115 Differential Impedance [ohms] 110 105 100 Sim (Same x-section) 95 Sim (Different x-sections) 90 85 80 2e-009 2.5e-009 3e-009 3.5e-009 4e-009 Time [sec] 8)10 90 0.35 0.33 53.5u 53.5u ſ 235u Zdiff=101 Ω Zdiff=104 Ω 235u 31 0.38

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4. Accuracy of EDA models

4.2.4 Edge of Connector Cable



- 1. Measurement and simulation of Interconnect model were done.
- 2. Simulation used by EDA models whom component manufacturer provides and measurement are nearly agreed.
- 3.Each simulator accepts S-parameters and directly simulate them.
- 4.It is necessary to note that a design value and an actual value might be different when EDA model of PCB is made.

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